

MA3JP02FG

Silicon epitaxial planar type

For high frequency switch

■ Features

- Small terminal capacitance C_t
- Small forward dynamic resistance r_f
- 2 elements type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

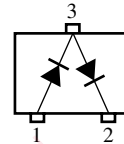
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Forward current	Single	I_F	100
	Double		65
Power dissipation	P_D	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Package

- Code
SMINI3-F2
- Pin Name
1: Anode 1
2: Cathode 2
3: Cathode 1
Anode 2

■ Marking Symbol: M6P

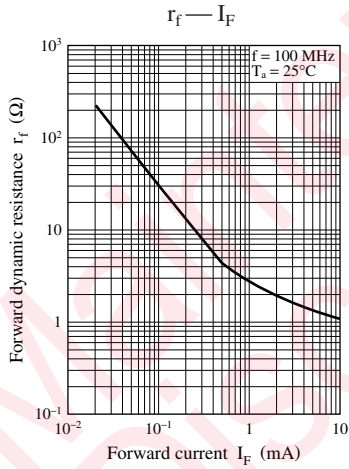
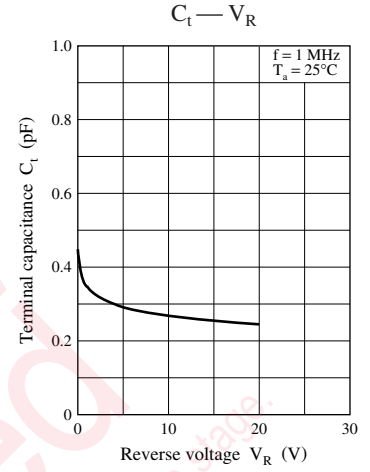
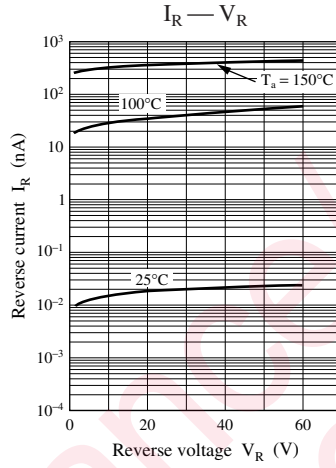
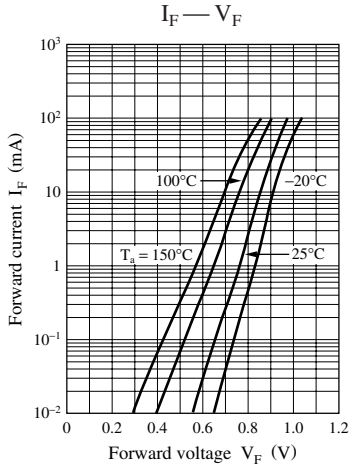
■ Internal Connection



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

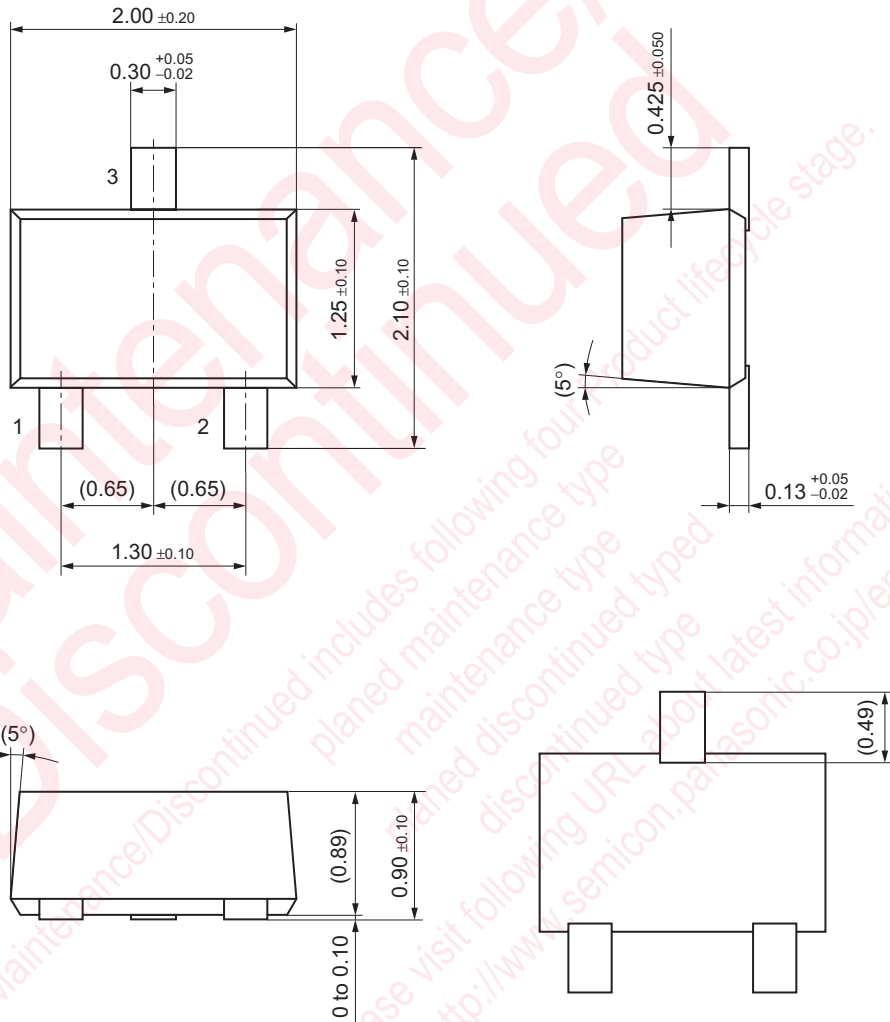
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10 \text{ mA}$			1.0	V
Reverse current	I_R	$V_R = 60 \text{ V}$			100	nA
Terminal capacitance	C_t	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$			0.5	pF
Forward dynamic resistance	r_f	$I_F = 10 \text{ mA}, f = 100 \text{ MHz}$			2.0	Ω

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.



SMini3-F2

Unit: mm



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